
ABSTRACT

The present invention provides a chassis heat dissipation device with a heat pipe heat dissipation fin, and a chassis having the same, wherein the chassis heat dissipation device comprises at least one heat sink placed on and under each circuit board, the heat sink comprises a top heat sink and a bottom heat sink, each heat sink comprises a plurality of rows of heat dissipation fins, the heat dissipation fin forms a vertical angle with the circuit board, the top heat sink and bottom heat sink sandwich the circuit board in between and are locked by screws into an integrated whole, and the heat of the computing power units is transferred to the heat dissipation fin and carried away by the flowing air; the heat sink is correspondingly placed on each column of chips of the computing power unit, heat pipes are embedded in the heat sink, a thermally conductive silicone grease is filled between the chips and the heat pipes to ensure sufficient connection, and heat pipes and the heat sink are connected by soldering; the heat pipes are evenly embedded in rows in the heat dissipation fin; the heat dissipation fin and heat pipes are made of different materials; the heat pipes have a convex cross section; the heat pipes embedded in the top heat sink and bottom heat sink are arranged in a crossed manner. The present invention can improve the heat dissipation capability of the whole machine and solve the problem about uneven temperature distribution of the whole machine.